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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/630,681	07/31/2003	Tetsuya Matsutani	2003_1039A 7670	
513	7590 04/21/2006	·	EXAMINER	
WENDERO	TH, LIND & PONACK	GURLEY, LYNNE ANN		
2033 K STRI SUITE 800	EET N. W.		ART UNIT	PAPER NUMBER
WASHINGTON, DC 20006-1021			2812	
			DATE MAILED: 04/21/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

## Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)		
10/630,681	MATSUTANI, TETSUYA		
Examiner	Art Unit /		
Lynne A. Gurley	2812		

Before the Filing of an Appeal Brief	Examiner	Art Unit	
	Lynne A. Gurley	2812	
The MAILING DATE of this communication appe	ars on the cover sheet with the c	correspondence add	ress
THE REPLY FILED 21 February 2006 FAILS TO PLACE THIS	APPLICATION IN CONDITION FO	R ALLOWANCE.	
1. The reply was filed after a final rejection, but prior to or on this application, applicant must timely file one of the follow places the application in condition for allowance; (2) a No a Request for Continued Examination (RCE) in compliance time periods:	wing replies: (1) an amendment, aff tice of Appeal (with appeal fee) in o ce with 37 CFR 1.114. The reply mo	idavit, or other evider compliance with 37 C	nce, which FR 41.31; or (3)
<ul> <li>a)</li></ul>	Advisory Action, or (2) the date set forth ater than SIX MONTHS from the mailing	g date of the final rejecti	on.
Examiner Note: If box 1 is checked, check either box (a) or to the two MONTHS OF THE FINAL REJECTION. See MPEP 7	• •	FIRST REPLY WAS F	ILED WITHIN
Extensions of time may be obtained under 37 CFR 1.136(a). The date have been filed is the date for purposes of determining the period of ex under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b) NOTICE OF APPEAL	tension and the corresponding amount shortened statutory period for reply original three months after the mailing da	of the fee. The appropring inally set in the final Offi	iate extension fee ice action; or (2) as
2. The Notice of Appeal was filed on A brief in comp filing the Notice of Appeal (37 CFR 41.37(a)), or any exte a Notice of Appeal has been filed, any reply must be filed AMENDMENTS	nsion thereof (37 CFR 41.37(e)), to	avoid dismissal of th	
3. The proposed amendment(s) filed after a final rejection,  (a) They raise new issues that would require further co  (b) They raise the issue of new matter (see NOTE below	nsideration and/or search (see NO		ecause
<ul> <li>(c) They are not deemed to place the application in befappeal; and/or</li> <li>(d) They present additional claims without canceling a</li> </ul>	tter form for appeal by materially re		the issues for
NOTE: (See 37 CFR 1.116 and 41.33(a)).			
4. The amendments are not in compliance with 37 CFR 1.1		mpliant Amendment	(PTOL-324).
<ul> <li>5. Applicant's reply has overcome the following rejection(s)</li> <li>6. Newly proposed or amended claim(s) would be all non-allowable claim(s).</li> </ul>	<u> </u>	timely filed amendme	ent canceling the
7.  For purposes of appeal, the proposed amendment(s): a) how the new or amended claims would be rejected is protected to the status of the claim(s) is (or will be) as follows: Claim(s) allowed: Claim(s) objected to: Claim(s) rejected: <u>15-17,22,24,26-33 and 35-65</u> . Claim(s) withdrawn from consideration:		II be entered and an e	explanation of
AFFIDAVIT OR OTHER EVIDENCE			
<ol> <li>The affidavit or other evidence filed after a final action, but because applicant failed to provide a showing of good an was not earlier presented. See 37 CFR 1.116(e).</li> </ol>			<del></del>
9. The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to a showing a good and sufficient reasons why it is necessary.	overcome <u>all</u> rejections under appear y and was not earlier presented. S	al and/or appellant fai ee 37 CFR 41.33(d)(	ils to provide a 1).
10. The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER		•	
11.  The request for reconsideration has been considered by See Continuation Sheet.			nce because:
<ul><li>12. ☐ Note the attached Information Disclosure Statement(s).</li><li>13. ☐ Other:</li></ul>			/ -
		James J. J.	aly
		Lynne A. Gurley Primary Patent Exa	ıminer

Art Unit: 2812

35 U.S.C. 102(b) US6,184,121 and U.S.C. 103: US 6,184,121, US 6,329,251 and US 5,656,556;.

Continuation of 11. does NOT place the application in condition for allowance because:

While the Examiner finds that the amendments have overcome the rejection under Buchwalter, the Examiner takes the position that in regard to the rejection of claim 27 under 35 U.S.C. 102(b) as being anticipated by Lee and in regard to the rejection of claims 28-31 under 35 U.S.C. 103 as being unpatentable over Lee in view of Wu and, further in view of Yang, Lee does show a first and second dielectric being deposited with contact holes through the first and second dielectric after both layers have been formed, as discussed in the first embodiment (column 5, lines 4-6; figures 9D and 10C). Although the vias are not explicitly shown, if the vias were made to connect through the first and second dielectric layers to the source/drain contacts, then the figures show that these portions of the dielectric layers have uniform thicknesses. So the rejection has been maintained.

In regard to the rejection of claims 15-17, 22, 24, 26 32-33 and 35-65 under 35 U.S.C. 103, the Wu reference is used to demonstrate the conventional processing of the substrate to have both closely spaced and widely spaced gates/interconnects and Ohno teaches that a contact hole may be made in two different dielectric layers after both are deposited in a similar structure (figs. 14B-16) as an alternative to forming the contact hole in one dielectric layer as shown in Wu. Using two different dielectric layers in interconnect and IMD structures is common practice for reasons such as lowering parasitic capacitance by combining different dielectric layers, thus decreasing the dielectric constant. The first dielectric is uniform in thickness at the portions through which the contact holes are formed as well in Ohno. Although the Examiner understands and has reviewed Applicant's remarks, the broadest interpretation of the prior art of record, especially Lee and Ohno still address the claimed limitations.